

**In the Specification**

**Delete paragraph [0016] beginning on page 3, and replace it with the following paragraph:**

[0016] In another aspect, the invention provides a method of processing greensheets for use as microelectronic substrates. The method includes providing a greensheet having a first and second ~~surfa~~essurface, and attaching a first support film to the first surface. The first support film and greensheet are then sequentially processed whereby the first support film constrains movement of the greensheet to prevent damage thereto such greensheet. This support film is preferably cast to the greensheet, has a thickness ranging from about 0.5 mils to about 6 mils and comprises a material that has sufficient rigidity to prevent damage to the greensheet during such processing steps.

**Delete paragraph [0025] beginning on page 5, and replace it with the following paragraph:**

Fig. 3B is a cross sectional ~~views~~view of Fig. 3A showing removal of the full area support film from the greensheet, preferably by a split ring vacuum mechanism/tool to assist peeling back the full area support film.

**Delete paragraph [0028] beginning on page 5, and replace it with the following paragraph:**

Fig. 5A is an alternate embodiment of the invention showing a cross sectional view of the greensheet having ~~the~~ a first full area support film thereon.

**Delete paragraph [0042] beginning on page 8, and replace it with the following paragraph:**

Preferably, the full area support film 20 comprises a material including, but not limited to, polyester, polyethylene, polyethylene ~~naphthalate~~ naphthalate (PEN), coated paper, polypropylene, silicone and composites including any of the above materials. Alternatively, the support film 20 attached to greensheet 20 may include a thin layer of metal, polymer, ceramic, cellulosic (i.e. cellulosic based paper or wood product) or combinations thereof having sufficient rigidity to prevent embossing or distortion of the greensheet during the process of punching vias therein. This rigid full area support layer is secured to the entire surface area of the greensheet 10 using an adhesive, including silicone, and may be removed just prior to either the screening process or just prior to the stacking process by UV or thermal.

**Delete paragraph [0046] beginning on page 9, and replace it with the following paragraph:**

Referring to Figs. 3A and 3B, during the removal, preferably peeling, of the full area support film from the greensheet, a vacuum may be adhered to the greensheet by suction as well as a holding means, preferably a split ring 39. Vacuum 30 and split ring 39 securely hold the greensheet during the process of removing the full area support film from such greensheet. The support film ~~4020~~ is detached from the greensheet by peeling back the support film ~~4020~~ in a direction preferably that is substantially parallel with the

greensheet, as shown by the arrow in Fig. 3B. The greensheet having vias therein, as discussed further below, may then be screened and patterned.